

**ATTACHMENT FOR CLAIM AMENDMENTS**

The following is a marked up version of each amended claim in which underlines indicates insertions and brackets indicate deletions.

1. (Amended) A circuit board[, the circuit board characterized by] comprising:  
a substrate;  
a first component [which is ]mounted on said substrate by a solder connection;  
a second component [which is ]mounted on said substrate with an anisotropic conductive film interposed therebetween; and  
a band-shaped region on the substrate which [extends in the shape of a band while including ] includes said second component, and which does not include said first component.

2. (Amended) A circuit board according to claim 1, [characterized in that] wherein said first component [is] further comprises one of a passive element [or] and a mechanism component, while said second component [is] further comprises a semiconductor device.

3. (Amended) A circuit board according to claim 1, [characterized in that] wherein said band-shaped region is wider than a pressing surface of a

thermocompression bonding head which is employed in mounting said second component to said substrate.

4. (Amended) A circuit board according to claim 1, [characterized in that] wherein an alignment mark is provided on said substrate outside said [belt] band-shaped region.

5. (Amended) A circuit board according to claim 1, [characterized in that] wherein the solder connection [includes] further comprises a reflow solder connection [treatment].

6. (Amended) A circuit board according to claim 1, [characterized in that] wherein a plurality of [said] first components are disposed on said substrate, and [that] said band-shaped region is located between the plurality of first components.

7. (Amended) A circuit board according to claim 6, [characterized in that] wherein said second component [is] further comprises one of a power source IC [or] and a power source LSI.

8. (Amended) A circuit board according to claim 1, [characterized in that] wherein said band-shaped region [is disposed extending] extends from one end of said substrate to another end of said substrate.

9. (Amended) A circuit board according to claim 1, [characterized in that] wherein said band-shaped region extends rectilinearly along said substrate.

10. (Amended) A circuit board according to claim 1, [characterized in that] further comprising wiring patterns [are] formed on said substrate in said band-shaped region.

11. (Amended) A circuit board according to claim 1, [characterized in that] further comprising a dummy electrode [is] formed at a position on said substrate corresponding to said second component.

12. (Amended) A display device [characterized by] comprising said circuit board of [the construction defined in] claim 1, and display means connected to [which] said circuit board[ is connected].

13. (Amended) A display device according to claim 12, [characterized in that] wherein said display means [is constructed of] further comprises a liquid crystal device which includes substrates, and [that] said circuit board is connected to said substrates.

14. (Amended) A display device according to claim 12, [characterized in that] wherein a plurality of [said] first components are disposed on said substrate, [that] said band-shaped region is located between the plurality of first components, and [that]

said second component [is] further comprises one of a power source IC, a power source LSI, a liquid crystal driving IC [or] and a liquid crystal driving LSI.

15. (Amended) A method of manufacturing a circuit board [characterized by] comprising:

the step of mounting a first component on a substrate by solder connection;

the step of arranging an anisotropic conductive film on a predetermined position of the substrate;

the step of arranging a second component on the anisotropic conductive film;  
and

the step of thermocompression-bonding the second component to said substrate with said anisotropic conductive film held therebetween;

wherein said step of arranging said anisotropic conductive film on the predetermined position of said substrate is performed after said step of mounting the first component on said substrate by the solder connection.

16. (Amended) A method of manufacturing a circuit board according to claim 15, [characterized in that] wherein said step of mounting said first component on said substrate by the solder connection includes a reflow treatment.